

Thunder High Power Products

Silicon N-Channel Planar Power MOSFET

Description

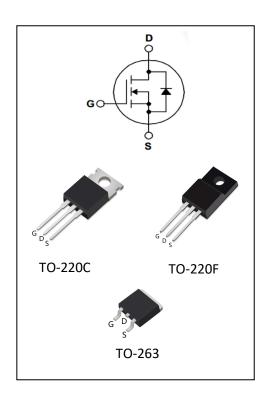
The TH52N20PC TH52N20PF TH52N20PN utilizes the latest processing techniques to achieve low on-resistance per silicon area. Additional features of this MOSFET are $150\,^{\circ}\mathrm{C}$ operating junction temperature and high repetitive peak current capability. These features combine to make this MOSFET a highly efficient, robust and reliable device for PDP driving applications. It can be used in a wide variety of applications.

General Features

- ●V_{DS}=200V,I_D=52A
- •Low ON Resistance, $R_{DS(ON)} = 33 \text{m} \Omega @V_{GS} = 10 \text{V}$, $I_D = 26 \text{A}$
- •Low reverse transfer capacitance
- ●Low Qg for fast response
- Short fall & rise times for fast switching
- ●100% single pulse avalanche energy Test

Application

- Power switching application
- Digital amplifier
- Adapter and charger



Product Summary

V _{DS}	200V
R _{DS(on)}	33mΩ
I _D	52A

Absolute Maximum Ratings

Parameter	Symbol	TH52N20PC	TH52N20PF	TH52N20PN	Unit
Drain-source voltage	$V_{ extsf{DS}}$	200			V
Continuous drain current T _C = 25°C (Silicon limit)	I _D	52			А
Pulsed drain current ($T_C = 25^{\circ}C$, t_p limited by T_{jmax})	I _{DM}	208			Α
Avalanche energy, single pulse (L=10mH, Rg=25 Ω)	E _{AS}	2900		mJ	
Gate-Source voltage	V_{GS}	±30		V	
Power dissipation (T _C = 25°C)	P _D	260 38 260			W
Operating junction and storage temperature	$T_{j}T_{stg}$	-55+150			°C





Thermal Resistance

Parameter	Symbol	TH52N20PC	TH52N20PF	TH52N20PN	Unit
Thermal resistance, junction – case.	RthJC	0.48	3.3	0.48	
Thermal resistance, junction – ambient(min.	RthJA	62.5	62.5	62.5	℃/W
footprint)					

Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)

Davamatar	Cumbal	value			Unit	Test Condition	
Parameter	Symbol	min.	typ.	max.	Ulli	Test Condition	
Static Characteristic							

Drain-source breakdown voltage	BV _{DSS}	200	-	-	V	V _{GS} =0V,I _D =250uA
Gate threshold voltage	$V_{GS(th)}$	2.0	-	4.0	٧	$V_{DS}=V_{GS}$, $I_D=250$ uA
Zero gate voltage drain current		-	-	1	μA	V_{DS} =200V, V_{GS} =0V T_j =25 °C
	I _{DSS}	-	-	10	μΑ	V_{DS} =160V, V_{GS} =0V T_{j} =125 $^{\circ}$ C
Gate-source leakage current	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 30 \text{V}, V_{DS} = 0 \text{V}$
Drain-source on-state resistance	R _{DS(on)}	-	33	40	mΩ	V _{GS} =10 V, I _D =26 A
Transconductance	g _{fs}	-	35	-	S	V _{DS} =40V, I _D =26A

Dynamic Characteristic

Input Capacitance	C _{iss}	-	3880	-	pF		
Output Capacitance	C _{oss}	-	420	-		V _{GS} =0V, V _{DS} =25V, f=1MHz	
Reverse Transfer Capacitance	C_{rss}	-	8	-			
Gate Total Charge	Q_g	-	56	-	nC		
Gate-Source charge	Q_{gs}	-	18	-		$V_{GS} = 10 \text{ V}, V_{DS} = 160 \text{ V},$ $I_D = 52 \text{ A}$	
Gate-Drain charge	Q_{gd}	-	23	-			
Turn-on delay time	t _{d(on)}	-	55	-		V _{DD} =100V, I _D =52A,	
Rise time	t _r	-	180	-	na		
Turn-off delay time	$t_{d(off)}$	-	49	-	ns	$R_G = 25 \Omega$	
Fall time	t _f	-	30	-			
Gate resistance	R_{G}	-	1	-	Ω	V_{GS} =0V, V_{DS} =0V, f=1MHz	



Body Diode Characteristic

Parameter	Value				l lmit	Tost Condition	
	Symbol	min.	typ.	max.	Unit	Test Condition	
Body Diode Forward Voltage	V_{SD}	-	-	1.5	V	$V_{GS} = 0 V, I_{DS} = 52 A$	
Body Diode Continuous Forward Current	Is	-	-	52	Α	T _C =25°C	
Body Diode Reverse Recovery Time	t _{rr}	-	165	-	ns	Tc=25°C,Is=52A,	
Body Diode Reverse Recovery Charge	Q _{rr}	-	1.4	-	μC	dI/dt=100A/us	

Typical Performance Characteristics

Fig 1: Output Characteristics

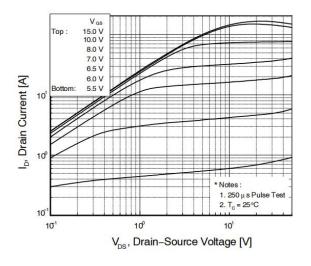


Fig 3: Rds(on) vs Drain Currentand

Gate Voltage

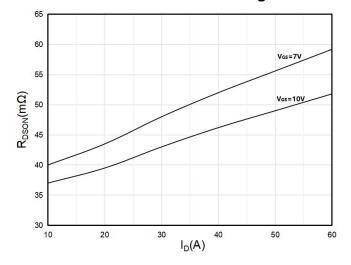


Fig 2: Transfer Characteristics

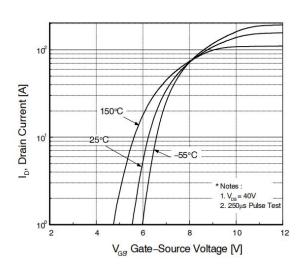
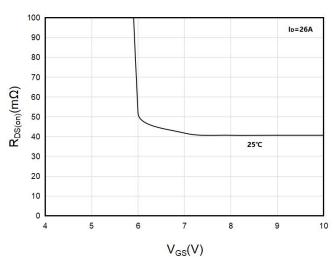


Fig 4: Rds(on) vs Gate Voltage



3



Fig 5: Rds(on) vs. Temperature

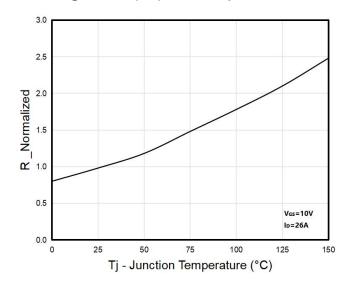


Fig 6: Capacitance Characteristics

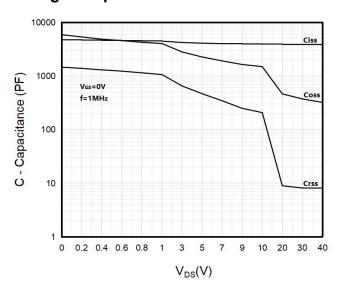


Fig 7: Gate Charge Characteristics

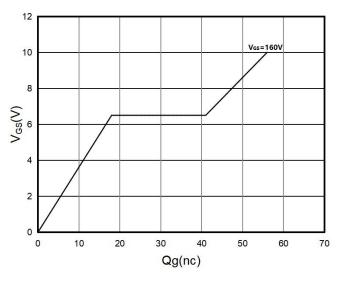


Fig 8: Body-diode Forward Characteristics

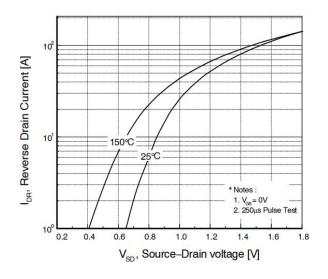


Fig 9: Power Dissipation

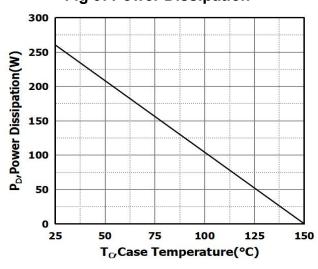


Fig 10: Drain Current Derating

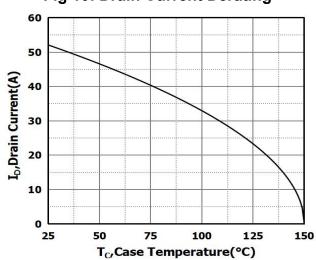


Fig 11: Safe Operating Area

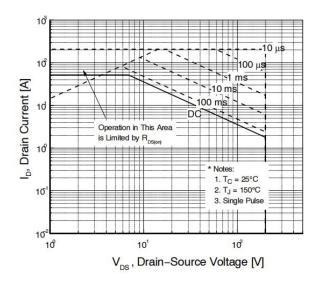
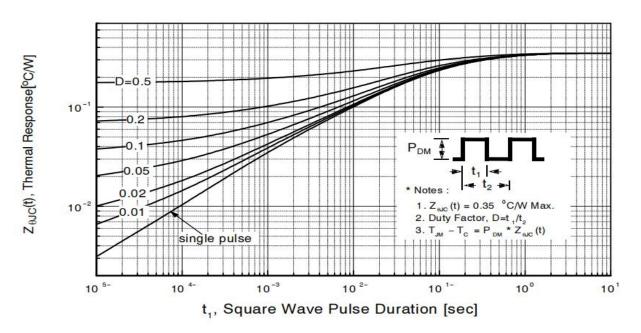


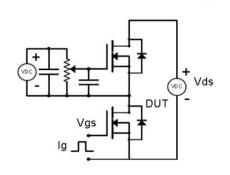
Fig 12: Max. Transient Thermal Impedance

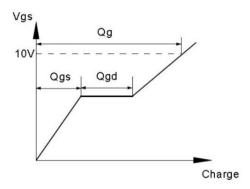


Rev.A02 5

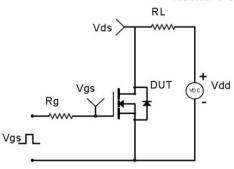
Test Circuit & Waveform

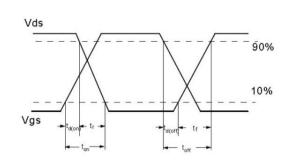
Gate Charge Test Circuit & Waveform



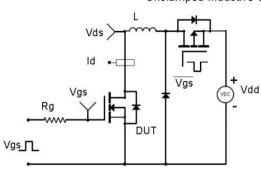


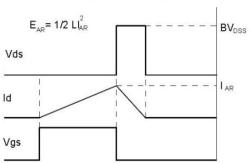
Resistive Switching Test Circuit & Waveforms



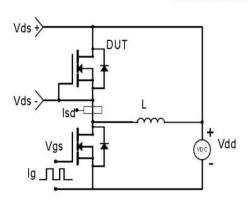


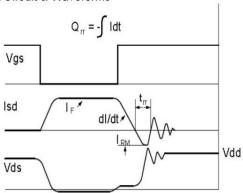
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

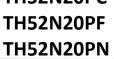




Diode Recovery Test Circuit & Waveforms





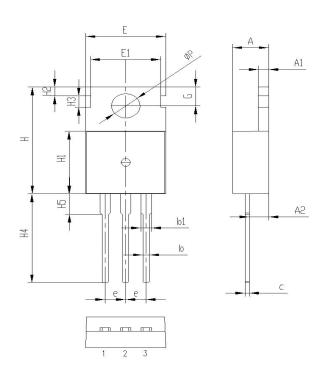




Package Information

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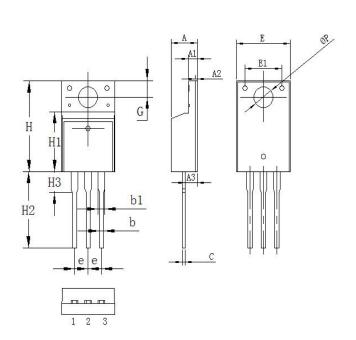
TO-220C PACKAGE



基本尺寸

	单位 mm						
Symbol -	Min	Nom	Max				
A	4. 30	4. 5	4. 70				
A1	1. 20	1. 30	1. 40				
A2	2. 20	2. 4	2. 60				
b	0.60	0.8	1.00				
b1	1. 20	1.30	1. 40				
С	0.40	0.5	0.60				
е	2. 44	2. 54	2. 64				
Е	9.80	10.0	10. 2				
E1	8. 50	8. 70	8. 90				
Н	15. 5	15. 7	15. 9				
H1	9.00	9. 2	9. 40				
Н2	1. 10	1. 34	1. 50				
НЗ	1. 50	1.7	1.90				
Н4	12. 9	13. 3	13.7				
Н5	2.80	3.0	3. 20				
G	2.60	2.8	3. 00				
ФР	3. 40	3.6	3.80				

TO-220F PACKAGE

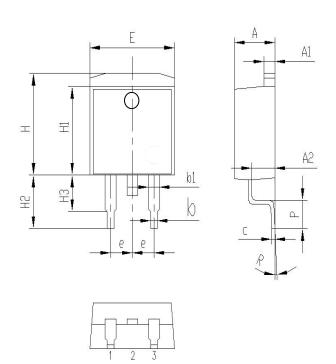


基本尺寸

C1-1		单位 mm					
Symbol	Min	Nom	Max				
A	4. 55	4. 75	4. 95				
A1	2.40	2. 60	2.80				
A2	0.40	0.60	0.80				
A3	2. 10	2. 30	2. 50				
b1	1. 10	1. 30	1.50				
b	0.60	0.80	1.00				
С	0.42	0. 50	0.58				
е	2. 30	2. 50	2. 70				
E	9. 9	10. 1	10. 3				
E1	6.8	7	7. 2				
Н	15.8	16.0	16. 2				
H1	9. 10	9. 30	9. 50				
H2	12.5	13.0	13. 5				
НЗ	3. 10	3. 30	3. 50				
G	3. 00	3. 20	3. 40				
ФР	3.00	3. 20	3. 40				



TO-263 PACKAGE



基本尺寸

Carrella - 1		单位 mm	
Symbol	Min	Nom	Max
A	4. 40	4.6	4. 80
A1	1. 17	1. 27	1. 37
A2	2. 40	2. 6	2. 80
b	0.60	0.8	1. 00
b1	1. 05	1. 25	1. 45
С	0. 28	0.38	0.48
e	2. 34	2.54	2.74
Е	9. 9	10. 1	10.3
Н	9. 90	10. 1	10.3
H1	8. 50	8.7	8. 90
H2	4. 80	5. 00	5. 20
H3	2. 60	2.8	3. 00
R	0°	3°	6°
Р	2. 40	2.70	3. 00

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